



**MECHANICAL OUTLINES  
DICTIONARY**

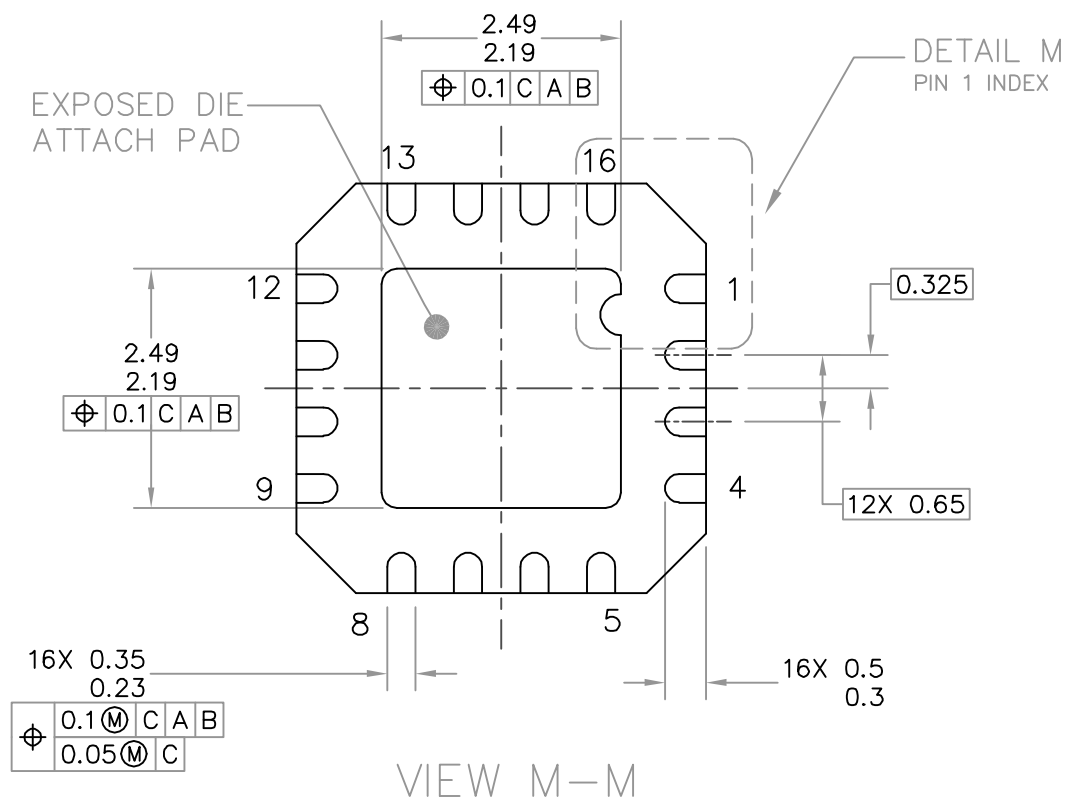
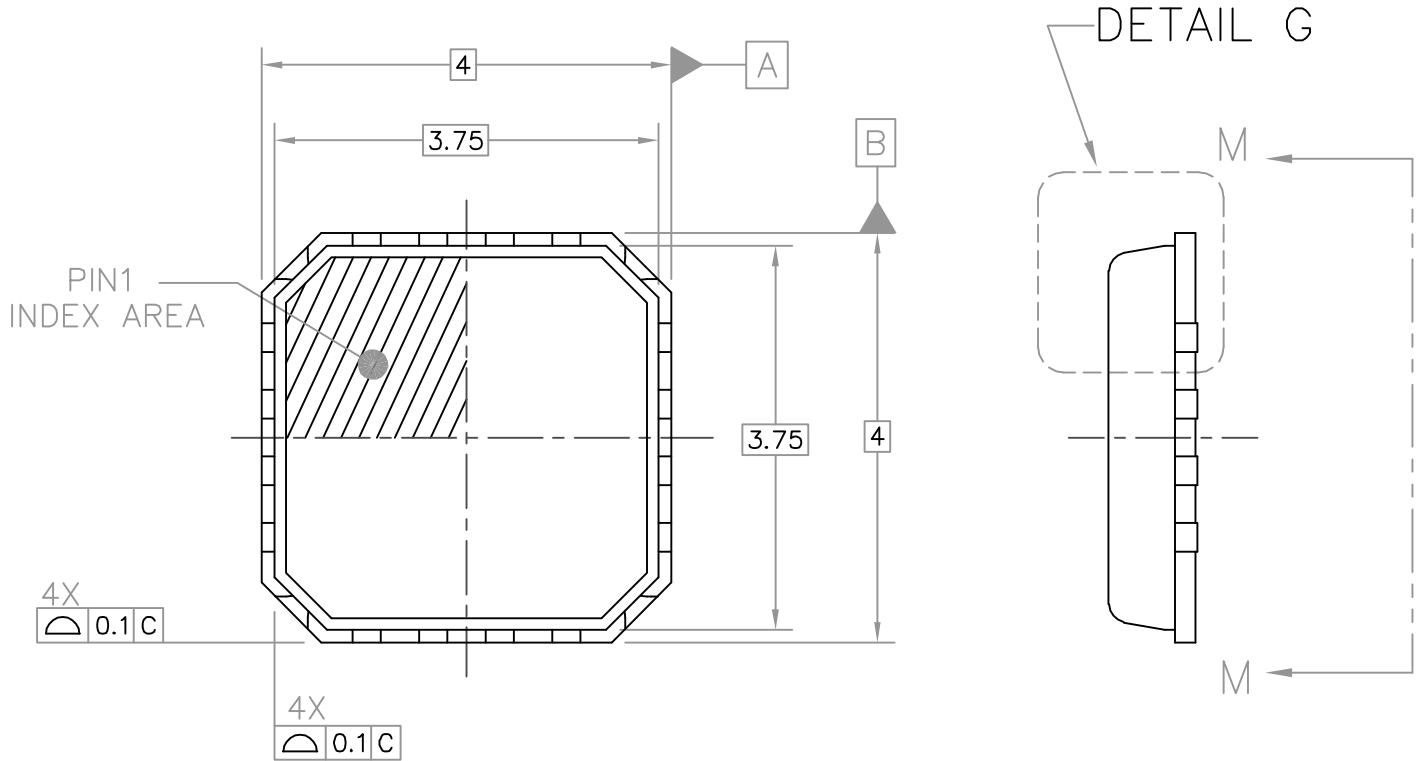
DOCUMENT NO: 98ASA10761D

PAGE: 1898

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REV: B



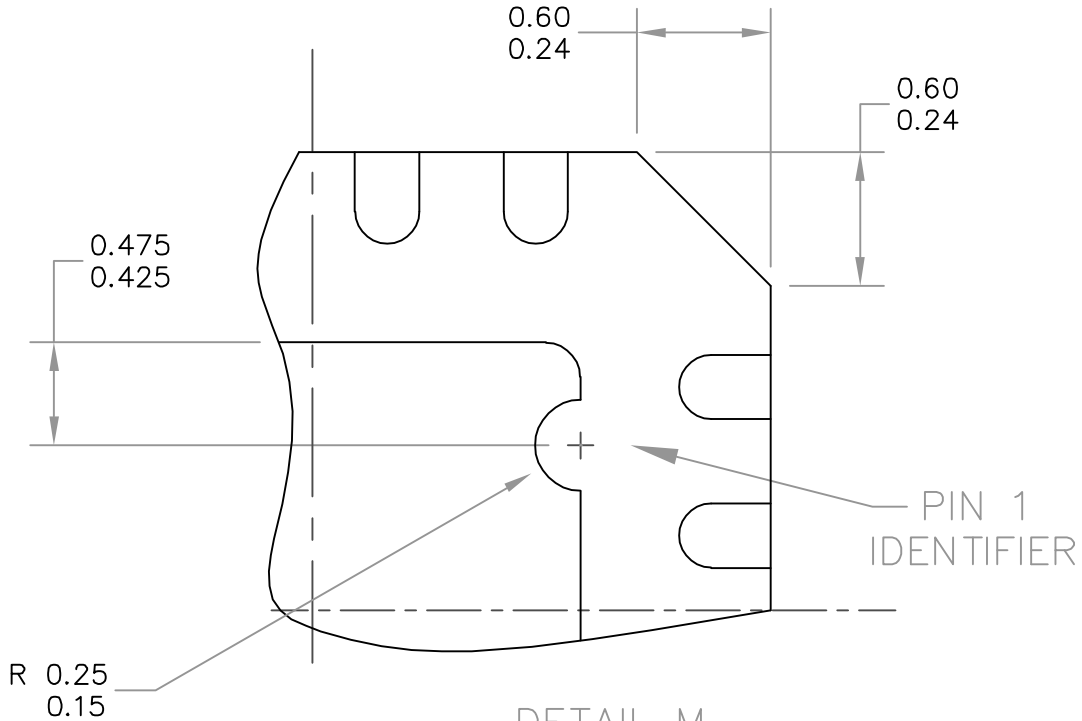
TITLE: THERMALLY ENHANCED QUAD  
FLAT NON-LEADED PACKAGE (QFN)  
16 TERMINAL, 0.65 PITCH (4 X 4 X 0.9)

CASE NUMBER: 1898-01

STANDARD: NON-JEDEC

PACKAGE CODE: 6216

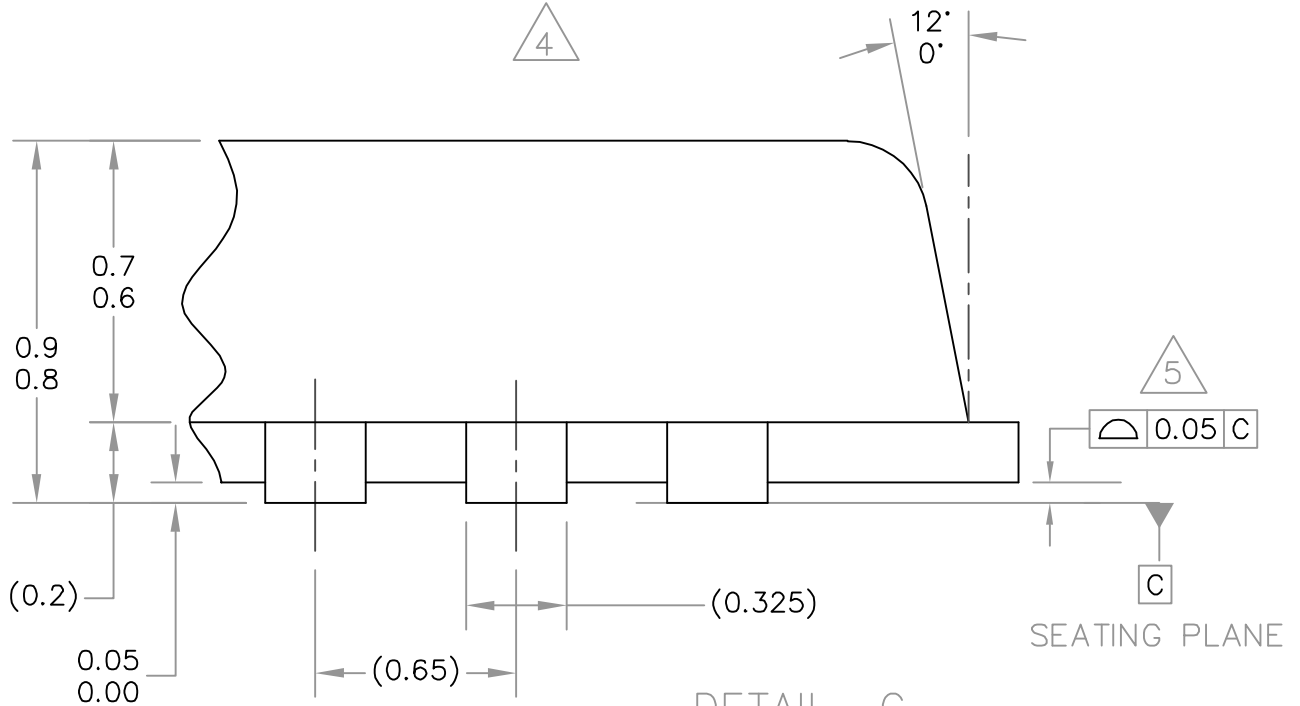
SHEET: 1 OF 4



DETAIL M  
PIN 1 BACKSIDE IDENTIFIER



// 0.1 C



DETAIL G  
VIEW ROTATED 90° CW

TITLE: THERMALLY ENHANCED QUAD  
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STANDARD: NON-JEDEC

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SHEET: 2 OF 4



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REV: B

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
5. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
6. MIN METAL GAP SHOULD BE 0.25MM.

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SHEET: 3 OF 4